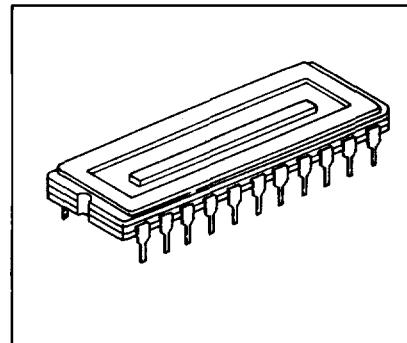


# TCD142D

(TENTATIVE)

The TCD142D is a high sensitive and low dark current 2048-element image sensor. The sensor can be used for facsimile, imagescanner and OCR. The device contains a row of 2048 photodiodes, which provide a 8 lines/mm (200 DPI) across a A4 size paper.

The device is operated by only 12V power supply, and mounted in 22-pin cerdip package with hermetic sealed optical glass window.



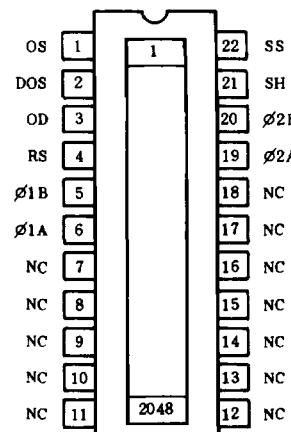
- Number of Image Sensing Elements : 2048
- Image Sensing Elements Size : 14 $\mu\text{m}$  by 14 $\mu\text{m}$  on 14 $\mu\text{m}$  centers
- Photo Sensing Region : High sensitive and low voltage dark signal pn photodiode.
- Clock : 2 phase
- Package : 22 pin Cerdip

## PIN CONNECTIONS

### MAXIMUM RATINGS (Note 1)

CHARACTERISTIC	SYMBOL	RATING	UNIT
Clock Pulse Voltage	V <sub>C</sub>		
Shift Pulse Voltage	V <sub>SH</sub>		
Reset Pulse Voltage	V <sub>RS</sub>		
Power Supply Voltage	V <sub>OD</sub>		
Operating Temperature	T <sub>opr</sub>	-25~60	°C
Storage Temperature	T <sub>stg</sub>	-40~100	°C

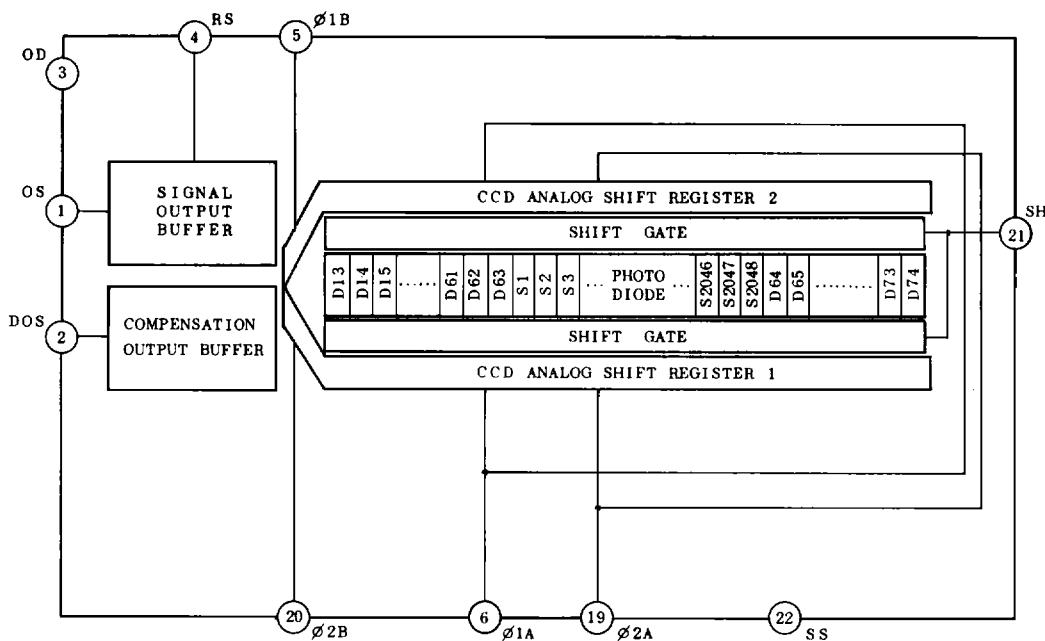
(Note 1) All voltage are with respect to SS terminals (Ground).



(TOP VIEW)

# TCD142D

## CIRCUIT DIAGRAM



## PIN NAMES

φ1A	Clock (Phase 1)
φ2A	Clock (Phase 2)
φ1B	Final Stage Clock (Phase 1)
φ2B	Final Stage Clock (Phase 2)
SH	Shift Gate
RS	Reset Gate
OS	Signal Output
DOS	Compensation Output
OD	Power
SS	Ground
NC	Non Connection

## OPTICAL/ELECTRICAL CHARACTERISTICS

( $T_a=25^\circ C$ ,  $V_{OD}=12V$ ,  $V_\phi=V_{SH}=V_{RS}=12V$  (PULSE),  $f_\phi=0.5MHz$ ,  $f_{RS}=1MHz$ , LOAD RESISTANCE=100k $\Omega$ )  
 $t_{INT}$ (INTEGRATION TIME)=10ms, LIGHT SOURCE=DAYLIGHT FLUORESCENT LAMP)

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT	NOTE
Responsivity	R	4.8	6.0	7.2	V/lx·sec	(Note 2)
Photo Response Non Uniformity	PRNU	-	-	10	%	(Note 3)
Register Imbalance	RI	-	-	3	%	(Note 4)
Saturation Output Voltage	V <sub>SAT</sub>	1.2	1.5	-	V	(Note 5)
Saturation Exposure	SE	0.17	0.25	-	lx·sec	(Note 6)
Dark Signal Voltage	V <sub>DRK</sub>	-	0.2	1	mV	(Note 7)
Dark Signal Non Uniformity	DSNU	-	0.2	2	mV	(Note 7)
DC Power Dissipation	P <sub>D</sub>	-	45	150	mW	
Total Transfer Efficiency	TTE	92	-	-	%	
Output Impedance	Z <sub>O</sub>	-	-	1	k $\Omega$	
Dynamic Range	DR	-	1500	-	-	(Note 8)
DC Signal Output Voltage	V <sub>OS</sub>	3.5	4.5	6.0	V	(Note 9)
DC Compensation Output Voltage	V <sub>DOS</sub>	3.5	4.5	6.0	V	(Note 9)
DC Mismach Voltage	V <sub>OS</sub> -V <sub>DOS</sub>	-	-	100	mV	

(Note 2) Responsivity for 2854K W-Lamp is 18V/lx·sec (Typ.)

(Note 3) Measured at 50% of SE (Typ.)

$$\text{Definition of PRNU: } \text{PRNU} = \frac{\Delta x}{\bar{x}} \times 100 \text{ (%)}$$

Where  $\bar{x}$  is average of total signal outputs and  $\Delta x$  is the maximum deviation from  $\bar{x}$  under uniform illumination.

(Note 4) Measured at 50% of SE (Typ.)

RI is defined as follows:

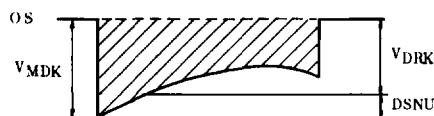
$$RI = \frac{\sum_{n=1}^{2047} |x_n - x_{n+1}|}{2047 \times \bar{x}} \times 100 \text{ (%)}$$

Where  $x_n$  and  $x_{n+1}$  are signal outputs of each pixel.  $\bar{x}$  is average of total signal outputs.

(Note 5) VSAT is defined as minimum Saturation Output Voltage of all effective pixels.

(Note 6) Definition of SE:  $SE = \frac{VSAT}{R}$

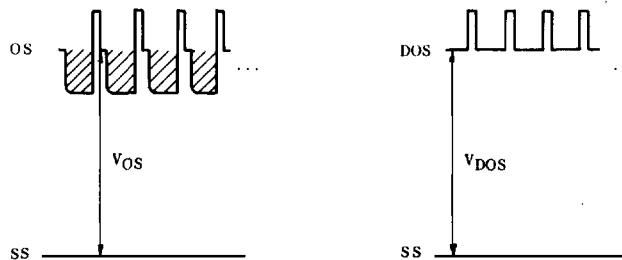
(Note 7) VDRK is defined as average dark signal voltage of all effective pixels.  
DSNU is defined as different voltage between VDRK and VMDK, when VMDK is maximum dark voltage.



(Note 8) Definition of DR:  $DR = \frac{VSAT}{VDRK}$

VDRK is proportional to  $t_{INT}$  (Integration time). So the shorter  $t_{INT}$  is, the wider DR is.

(Note 9) DC Signal Output Voltage and DC Compensation Output Voltage are defined as follows:



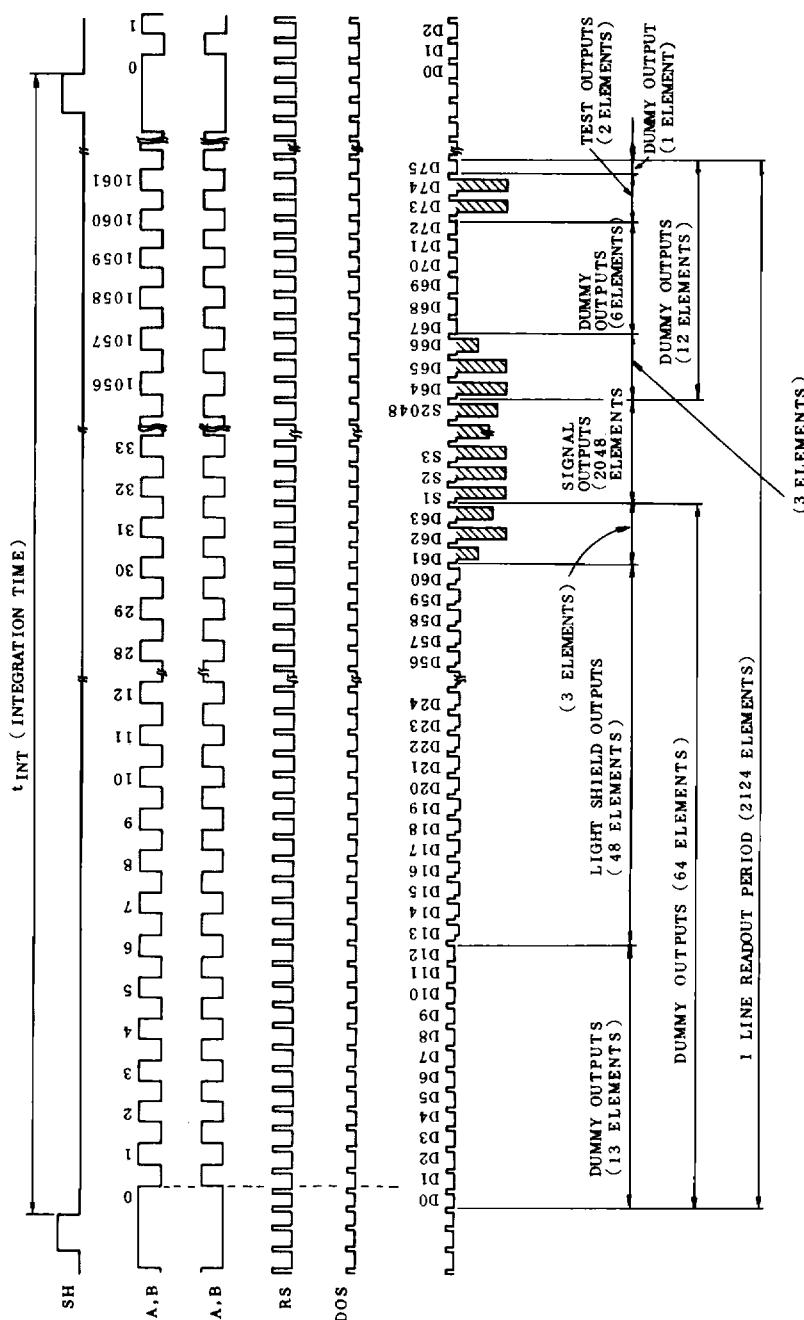
**OPERATING CONDITION**

CHARACTERISTIC		SYMBOL	MIN.	TYP.	MAX.	UNIT
Clock Pulse Voltage	H-Level	$V_\phi$	$V_{OD-1}$	$V_{OD}$	$V_{OD}$	V
	L-Level		0	0.5	0.8	
Shift Pulse Voltage	H-Level	$V_{SH}$	$V_{OD-1}$	$V_{OD}$	$V_{OD}$	V
	L-Level		0	0.5	0.8	
Reset Pulse Voltage	H-Level	$V_{RS}$	$V_{OD-1}$	$V_{OD}$	$V_{OD}$	V
	L-Level		0	0.5	0.8	
Power Supply Voltage		$V_{OD}$	11.4	12	13	V

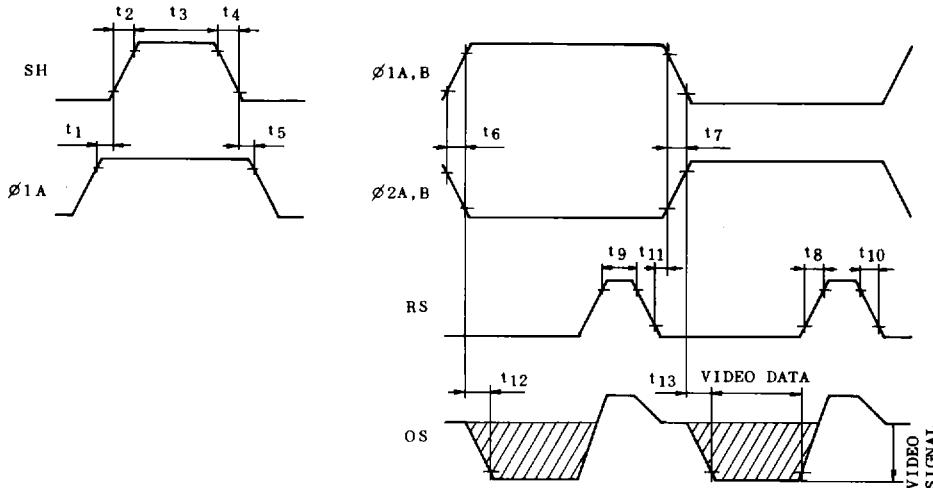
**CLOCK CHARACTERISTICS (Ta=25°C)**

CHARACTERISTIC	SYMBOL	MIN.	TYP.	MAX.	UNIT
Clock Pulse Frequency	$f_\phi$	-	0.5	5	MHz
Reset Pulse Frequency	$f_{RS}$	-	1.0	10	MHz
Clock Capacitance	$C_{\phi A}$	-	400	500	pF
Final Stage Clock Capacitance	$C_{\phi B}$	-	10	25	pF
Shift Gate Capacitance	$C_{SH}$	-	150	250	pF
Reset Gate Capacitance	$C_{RS}$	-	10	25	pF

## TIMING CHART



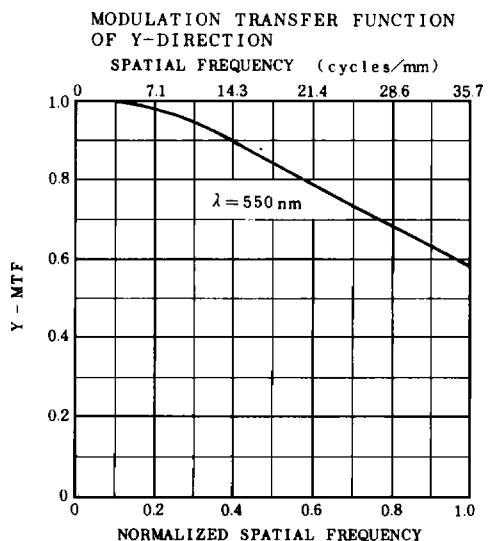
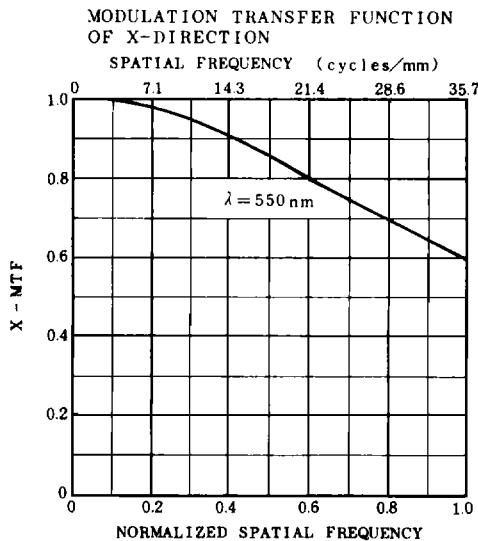
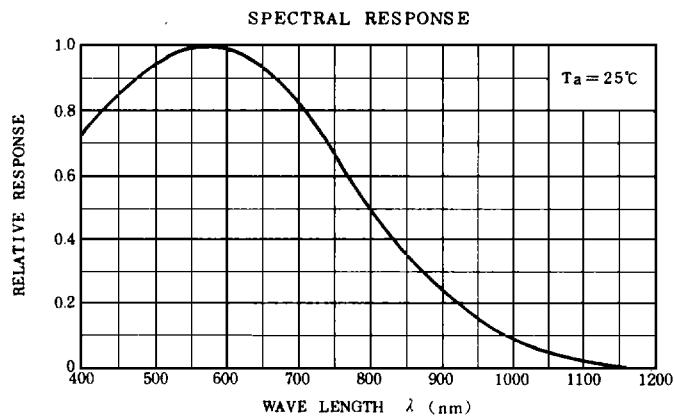
## TIMING REQUIREMENTS



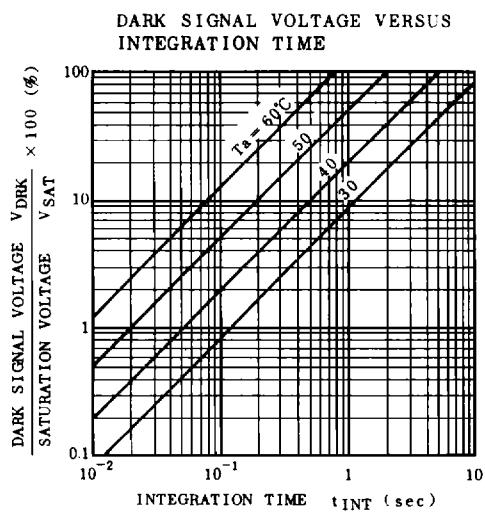
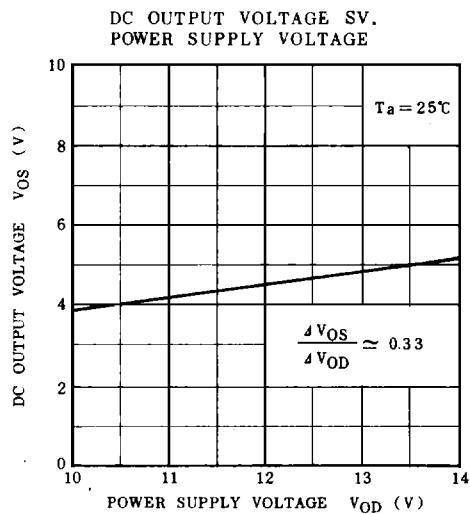
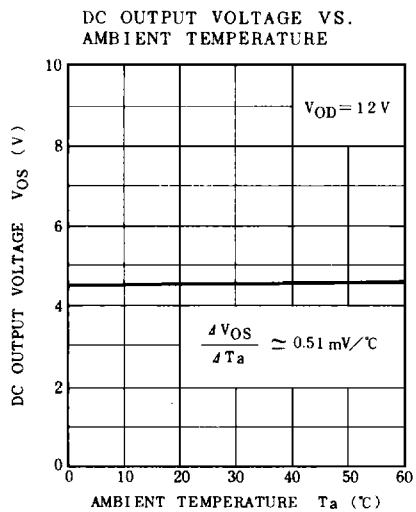
CHARACTERISTIC	SYMBOL	MIN.	TYP. (Note 10)	MAX.	UNIT
Pulse Timing of SH and $\phi 1A$	$t_1, t_5$	0	100	-	ns
SH Pulse Rise Time, Fall Time	$t_2, t_4$	0	50	-	ns
SH Pulse Width	$t_3$	200	1000	-	ns
$\phi 1A, B$ , $\phi 2A, B$ Pulse Rise Time, Fall Time	$t_6, t_7$	0	100	-	ns
RS Pulse Rise Time, Fall Time	$t_8, t_{10}$	0	20	-	ns
RS Pulse Width	$t_9$	40	250	-	ns
Pulse Timing of $\phi 1B, \phi 2B$ and RS	$t_{11}$	10	250	-	ns
Video Data Delay Time (Note 11)	$t_{12}, t_{13}$	-	50	-	ns

(Note 10) TYP. is the case of  $f_{RS}=1\text{MHz}$ .(Note 11) Load Resistance is  $100\text{k}\Omega$ .

## TYPICAL PERFORMANCE CURVES

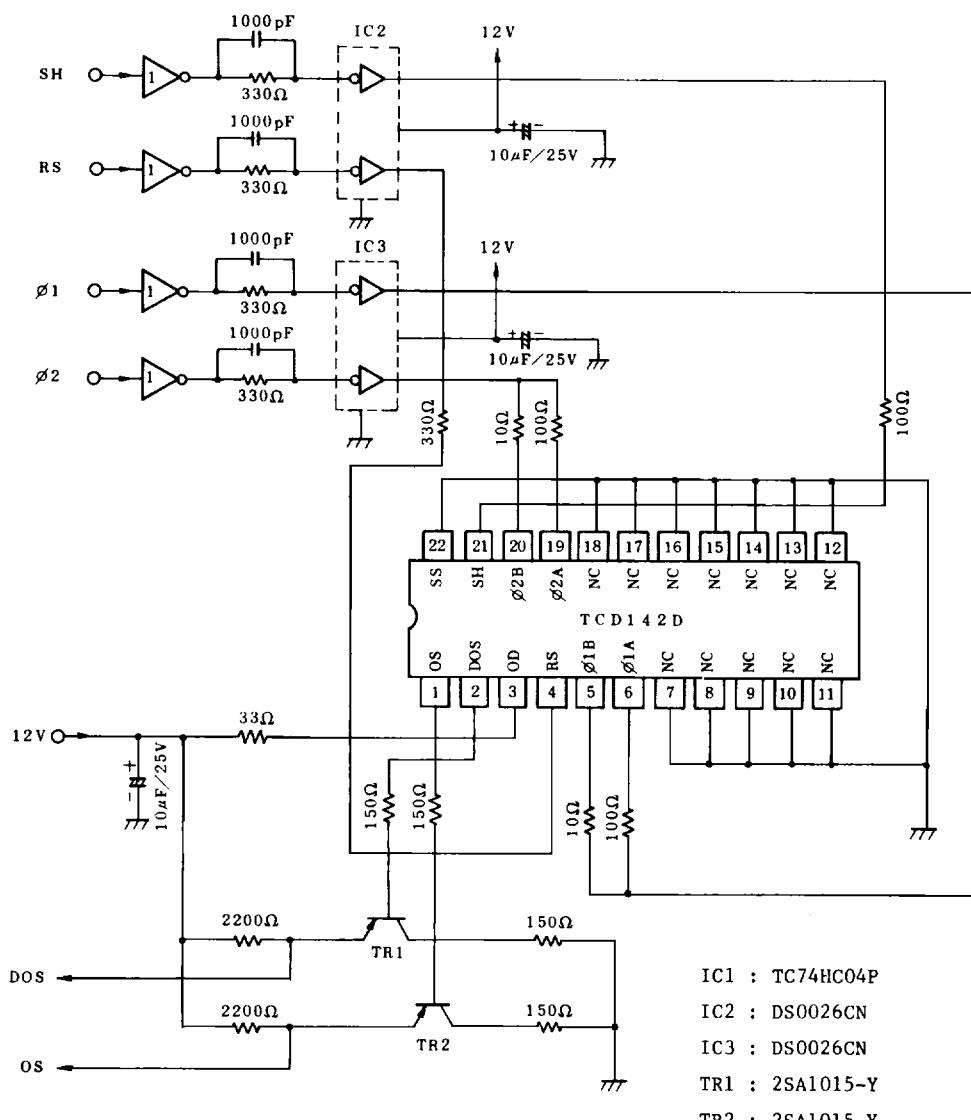


TYPICAL PERFORMANCE CURVES(Cont'd)



# TCD142D

## TYPICAL DRIVE CIRCUIT



**CAUTION****1. Window Glass**

The dust and stain on the glass window of the package degrade optical performance of CCD sensor.

Keep the glass window clean by saturating a cotton swab in alcohol and lightly wiping the surface, and allow the glass to dry, by blowing with filtered dry N<sub>2</sub>.

Care should be taken to avoid mechanical or thermal shock because the glass window is easily to damage.

**2. Electrostatic Breakdown**

Store in shorting clip or in conductive foam to avoid electrostatic breakdown.

**3. Incident Light**

CCD sensor is sensitive to infrared light.

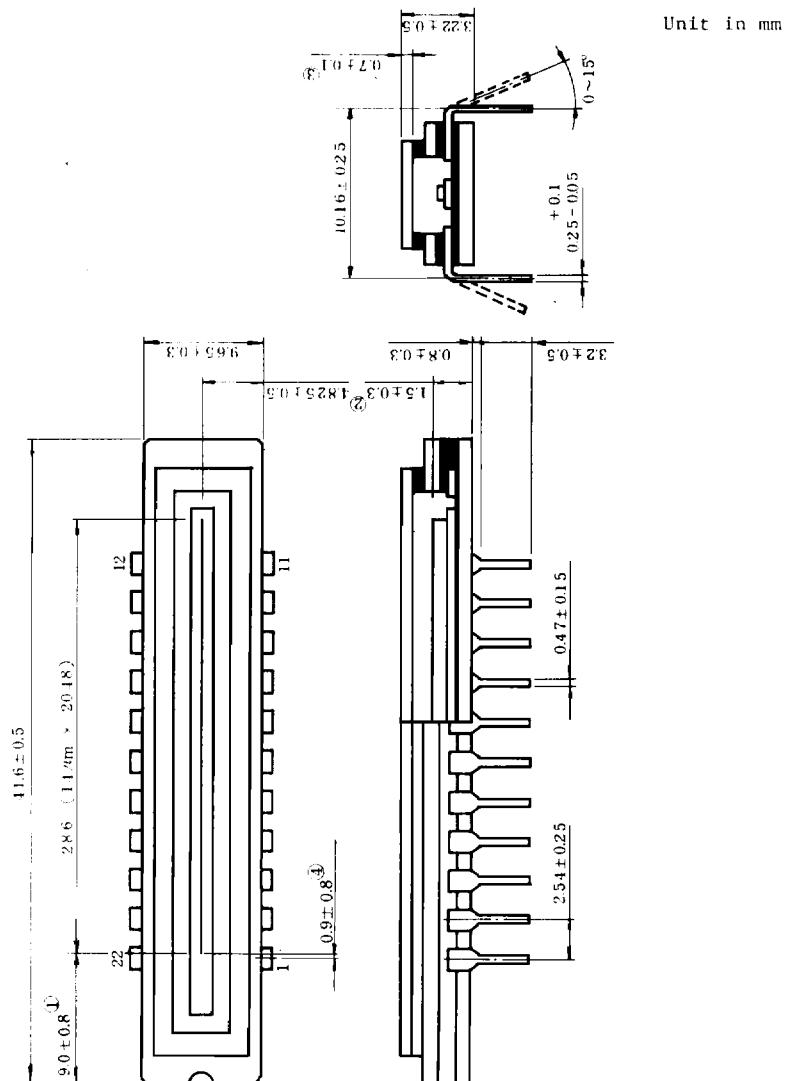
Note that infrared light component degrades resolution and PRNU of CCD sensor.

**4. Lead Frame Forming**

Since this package is not stout against mechanical stress, you should not reform the lead frame.

We recommend to use a IC-inserter when you assemble to a PCB.

## PACKAGE OUTLINE



- (1) No.1 SENSOR ELEMENT (S1) TO EDGE OF PACKAGE
- (2) TOP OF CHIP TO BOTTOM OF PACKAGE
- (3) GLASS THICKNESS ( $n=1.5$ )
- (4) No.1 SENSOR ELEMENT(S1) TO CENTER OF No.1 pin.